DOM No.	2	000101	40.01.1			DON		Deserve	1.6 2022	
								December	16, 2022	
				tional Fa	o site for	r selec				
Customer Cont	Manager			Dept:		Quality Se	uality Services			
Proposed 1 st S	6, 2023 Samplaccep					Jan 16, 20	n 16, 2023*			
*Sample reque	ests receiv	ed after	[.] Ja nua ry	January 16, 2023 will not be suppo						
Change Type:										
Assembly S	ite		Desig					Bump Site		
Assembly P			Data Sheet				Wafer Bump Material			
Assembly M			Part number change				Wafer Bump Process			
	Specificatio		Test Site							
□ Packing/Sh	ipping/Label	ing	Test Process				Wafer Fab Materials			
							Wafer	r Fab Process		
	-		PCI	Deta	IS					
Description of				1:6:	Lie					
Texas Instrumer additional Wafer										
	Current Si	te			Ac	dditio	nal Site			
Current Fab Site	Process		Wafer Jiameter	Addit Fab	ional Site	Process		Wafer Diamete	r	
RFAB	LBC9		300 mm	DM	DS6	LBC9		300 mm		
Reason for Cha Continuity of Su Anticipated im None	pply pact on Fo						/ (positi	ve / nega	tive):	
Changes to pro		ificatio	n resultin	g from t	his PCN	l:				
		Chip	Site Origin		Chip Site Country Code (2					
Chip Site		•	de (20L)	Chip	o Site Co	untry	L) Chip	Site City		
RFAB			RFB		USA				nardson	
DMOS6			DM6			USA		D	allas	
Sample product TEXAS INSTRUMENTS MADE IN: Mala 2DC: 2/260C/J MSL 1 /235C/U OPT: ITEM: LBL: 5A (Product Affect	5 ysia YEAR SEAL 03/29 L)T0:175	€4 G4 DT_/04	actual prod		1P) SN (a) 20	00 DT: 39 Y(1T)	(D) () 9590471) 75234	1LA 83512 35317 :0:USA		
DRV5032FADB		V5032FE	BDBZR	DRV50	32FCDB	ZR				
DRV5032FADB		V5032FE			DRV5032FCDBZT					
	DRV5052FADDZI DRV5052FE			-						

Qualification Report Approve Date 15-FEBRUARY -2022

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: DRV5032FADBZR	Qual Device: DRV5032FBDBZR	Qual Device: DRV5032FCDBZR	QBS Reference: SN012776B0YBHR	QBS Reference: DRV5015A2EDBZRQ1	QBS Reference: DRV5015A3EDBZRQ1	QBS Reference: TMAG5231B1DQDBZR	QBS Reference: DRV5032FBDBZR	QBS Reference: DRV5032FCDBZR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	-	-	1/77/0	-	-
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	1/77/0	2/156/0	-	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	1/77/0	2/154/0		-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	-	-	3/231/0	-	-
тс	A4	Temperature Cycle	-40C/85C	1000 Cycles	-	-	-	3/231/0	-	-	-		-
тс	A4	Temperature Cycle	-55/125C	700 Cycles	-	-	-	3/231/0			-	-	-
тс	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	-		3/231/0	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	-		3/231/0	-	-
HTSL	A6	High Temperature Storage Life	175C	1000 Hours	-	-	-	-	-	1/77/0	-	-	-
HTOL	B1	CL (FF)	125C	1000 Hours	-	-	-	1/45/0	-	-	-	-	-
HTOL	B1	CL (FS)	125C	1000 Hours	-	-	-	1/32/0	-	-		-	-
HTOL	B1	CL (SF)	125C	1000 Hours	-	-	-	1/32/0	-	-	-	-	-
HTOL	B1	CL (SS)	125C	1000 Hours	-	-	-	1/45/0	-	-	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	3/231/0			-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	-	-	3/231/0	-	-
HTOL	B1	Life Test	150C	1000 Hours	-	-	-	-	-	3/231/0	-	-	-
ELFR	B2	ELFR	125C	48 Hours	-	-	-	3/3000/0	-	-	-	-	-
ELFR	B2	Early Life Failure Rate	150C	48 Hours	-	-	-	-	-	2/1600/0	-	-	-

QBS: Qual By Similarity

Qual Device DRV5032FADBZR is qualified at MSL1 260C

Qual Device DRV5032FBDBZR is qualified at MSL1 260C

Qual Device DRV5032FCDBZR is qualified at MSL1 260C

· Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contact below or your local Field Sales Representative.

Location	E-Mail					
WW Change Management Team	PCN ww admin team@list.ti.com					

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